

UHF-Band RF Modulator for VCR

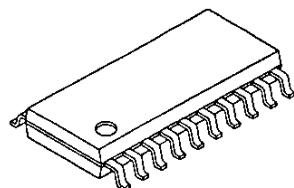
Description

The CXA1733M is a UHF-band RF modulator which converts the frequency of audio and video signals. Some circuits which comprise this IC are a UHF oscillator, video clamp, white clip, video modulator, audio FM modulator, test pattern signal generator, and an intercarrier SW.

Features

- Low voltage of 5V
- Wide bandwidth 470 to 750MHz
- UHF oscillator greatly reduces external parts
- Sharp white clip circuit
- Built-in voltage regulator can accept large fluctuation of supply voltage
- Video input of 0.5Vp-p for general purpose use
- Mixer simplifies RF unit design
- Picture/sound ratio is adjustable with external parts
- Test pattern signal generator
- Inter carrier switch

20 pin SOP (Plastic)



Structure

Bipolar silicon monolithic IC

Applications

PAL system VCR

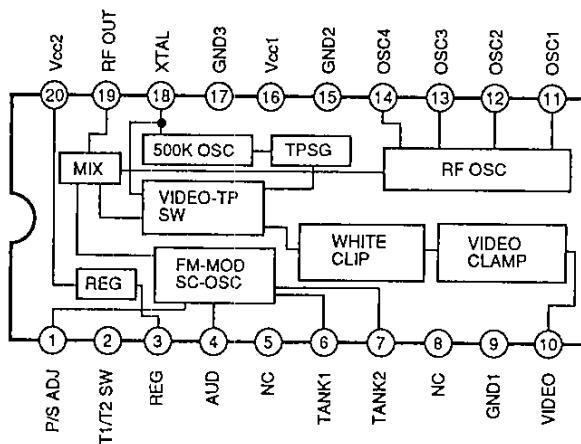
Absolute Maximum Ratings ($T_a=25^\circ\text{C}$)

Supply voltage	Vcc	7	V
Operating temperature	Topr	-20 to +75	°C
Storage temperature	Tstg	-55 to +150	°C
Allowable power dissipation	PD	350	mW

Recommended Supply Voltage Range

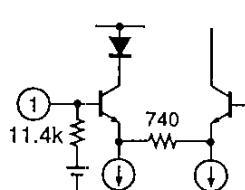
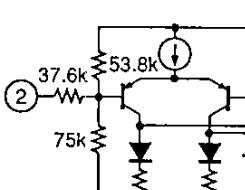
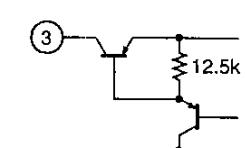
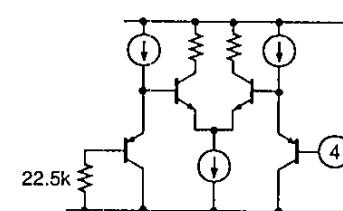
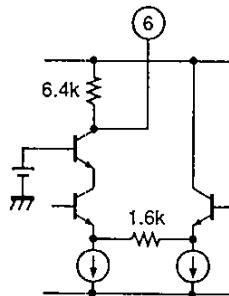
Supply voltage Vcc 5.0 ± 0.5 V

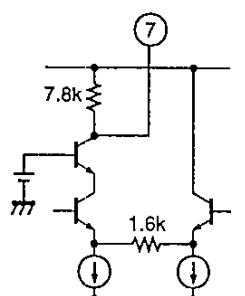
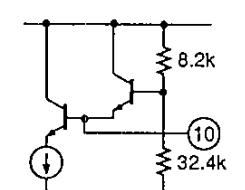
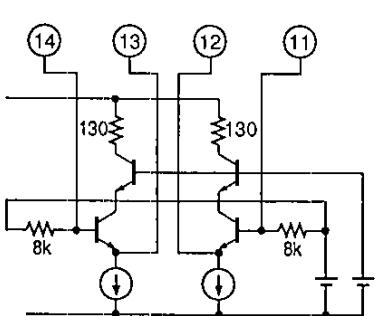
Block Diagram and Pin Configuration

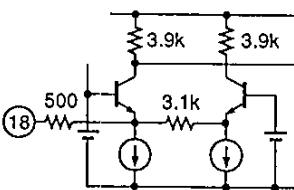
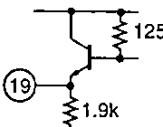


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Pin Description and Equivalent Circuit

Pin No.	Symbol	Pin voltage (V) Typical	Equivalent circuit	Description
1	P/S ADJ	1.8		P/S adjustment (Adding a capacitor between Pin 1 and GND increases P/S ratio.) Video modulation depth adjustment (Adding a resistor between Pin 1 and GND increases the modulation depth; adding a resistor between Pin 1 and 3 decreases the modulation depth.)
2	T1/T2 SW	2.4		T1/T2 SW. T1 for GND. T2 for OPEN.
3	REG OUT	4.1		Regulator output.
4	AUDIO IN	0		Audio input.
5	NC			
6	TANK1	3.1		5.5MHz audio tank coil connection.

Pin No.	Symbol	Pin voltage (V) Typical	Equivalent circuit	Description
7	TANK2	2.9		6.0MHz audio tank coil connection.
8	NC			
9	GND1			GND for audio.
10	VIDEO IN	2.6		Video input.
11 12 13 14	OSC1 OSC2 OSC3 OSC4	2.5 1.7 1.7 2.5		Oscillator pin.
15	GND2			GND for oscillator.
16	VCC1			Power supply for oscillator.
17	GND3			GND for RF.

Pin No.	Symbol	Pin voltage (V) Typical	Equivalent circuit	Description
18	TPSG SW	1.2		Crystal is connected to this pin. TPSG is OFF for GND.
19	RF OUT	4.1		RF output.
20	Vcc2			Power supply for RF/audio.

Electrical Characteristics 1Refer to Electrical Characteristics Test Circuit ($T_a=25^\circ C$, $V_{cc}=5V$, $f_P=591.25MHz$)

Item	Symbol	Conditions	Min.	Typ.	Max.	Unit
Supply current	I _{cc}	V ₁ (VIDEO IN) and V ₂ (AUDIO IN) at no signal	23	32	40	mA
Video output level	V _o	*1	78.7	81.2	83.7	dB μ V
Video modulation depth	m _p	V ₁ =0.5Vp-p, FLAT FIELD signal input	72	78.5	86	%
Max. video modulation depth (During limiter operation)	m _p (Max.)	V ₁ =1.0Vp-p, FLAT FIELD signal input	92	95.5	99	%
Chroma beat	V _{cb}	V ₁ =4.43MHz, 0.5Vp-p sine wave input *5	68	78	—	dB
Sync crush level	Δ Sync	V ₁ =0.5Vp-p, FLAT FIELD signal input Δ Sync= $(1 - \frac{S}{W} \cdot \frac{10}{4}) \times 100$	—	2	5	%
Differential gain	DG	STAIR STEP signal input V ₁ =0.5Vp-p *2	0	1.6	5	%
Differential phase	DP	STAIR STEP signal input V ₁ =0.5Vp-p *2	-5	0	5	deg
Video 2nd-harmonic wave ratio	V _{VH}	V ₁ =0.5Vp-p, 1MHz sine wave input*3	48	52.5	—	dB
PS ratio	V _{ps}	V ₁ =no input, fs=5.5MHz	11.5	14	16.5	dB
Audio FM modulation sensitivity	βS_1 (T1)	V ₂ =100mVp-p, 1kHz sine wave input	fs=5.5MHz	0.37	0.42	0.475 kHz/mV
	βS_2 (T2)	fs frequency change/ 0.1V *6				
Audio distortion	THD	V ₂ =1kHz sine wave input *4	0	0.4	1	%
Audio S/N ratio	ASN	V ₂ =1kHz sine wave input 0dB at fs=5.5MHz with 60kHz deviation V ₁ =STAIR STEP signal input (rms measurement)	45	54	—	dB
Max. audio FM modulation depth	m _s (Max.)	V ₂ =1Vp-p, 1kHz sine wave input (T1) fs frequency change (kHz)/ 100 kHz $\times 100$	380	415	—	%
Audio 2nd-harmonic wave ratio	V _{s2}	Difference between video carrier (V ₁ =no input) and 2nd-harmonic wave, at PS ratio of 14dB conversion	52	57	—	dB
TPSG synchronization period	T _{Mtp}	S ₂ OFF	62	64	66	μ sec
TP video modulation depth	M _{tp}	S ₂ OFF	70	80	90	%
Supply current when TPSG is ON	I _{cc Ton}	S ₂ OFF	24	34	43	mA

Classification of Audio Modulation Sensitivity (T1, fs=5.5MHz)

Marking	Audio modulation sensitivity	Unit
CXA1733M-1	0.4 to 0.445	kHz/mV
CXA1733M-2	0.37 to 0.41	kHz/mV
CXA1733M-3	0.435 to 0.475	kHz/mV

Electrical Characteristics 2

1. Video S/N	50dB (min.), 58dB (typ.)
2. Video amplitude frequency characteristics (at 1MHz reference)	Within ± 1 dB at 0.5 to 5MHz
3. APL variation (Normalized to APL 50%)	Within $\pm 2\%$ at 10 to 90%
4. Pin 4 input impedance	1M Ω and above
5. Pin 10 input impedance	1M Ω and above

*1. Spectrum analyzer with 50Ω input impedance should be used to test video output level. Measured value V_o (dBm) is used to calculate output according to following relationship:

Output ($\text{dB } \mu$) = $V_o (\text{dBm}) + 107$ 50Ω terminal direct reading value

*2. Measured after demodulating by standard demodulator.

*3. fc+2MHz component of V1 carrier (fc) level.

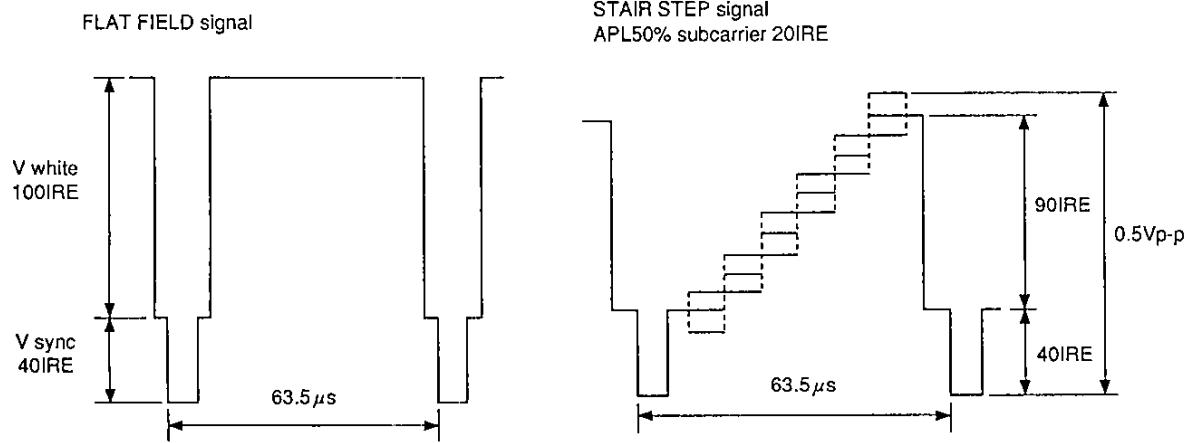
*4. Adjust the V₂ level to obtain an FM deviation of $\pm 30\text{kHz}$ and measure the harmonic distortion after demodulating V₀ with a standard demodulator.

*5. Value determined by measuring ratio (dB) of chroma beat to video carrier level when V1=no signal by spectrum analyzer.

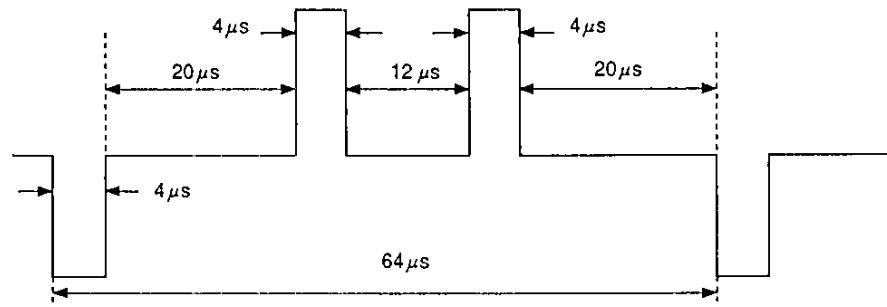
*6. R1 (12k Ω) of the Electrical Characteristics Test Circuit is added for obtaining a better match between the

audio modulation sensitivity classifications and the actual pre-emphasis.

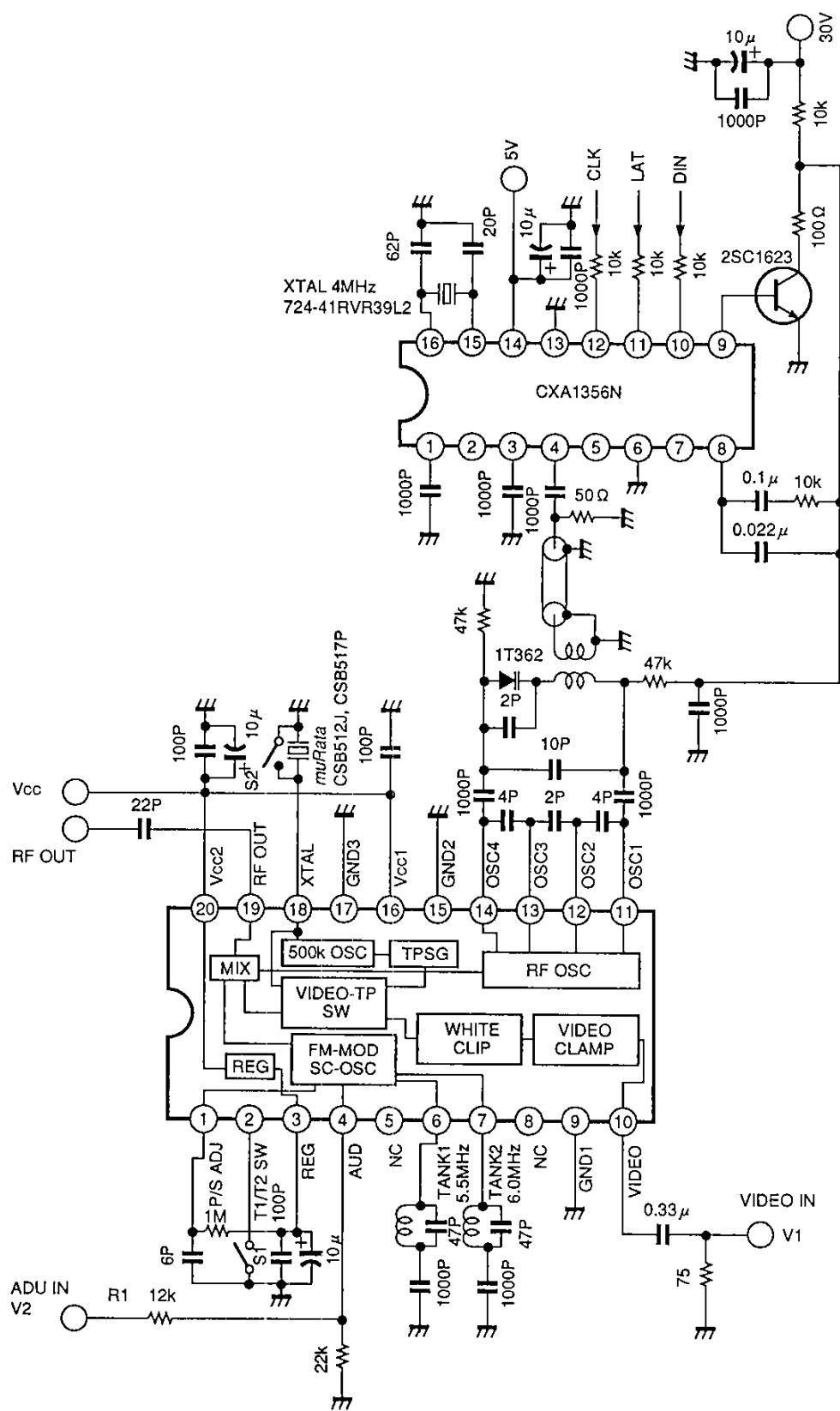
Input Waveform



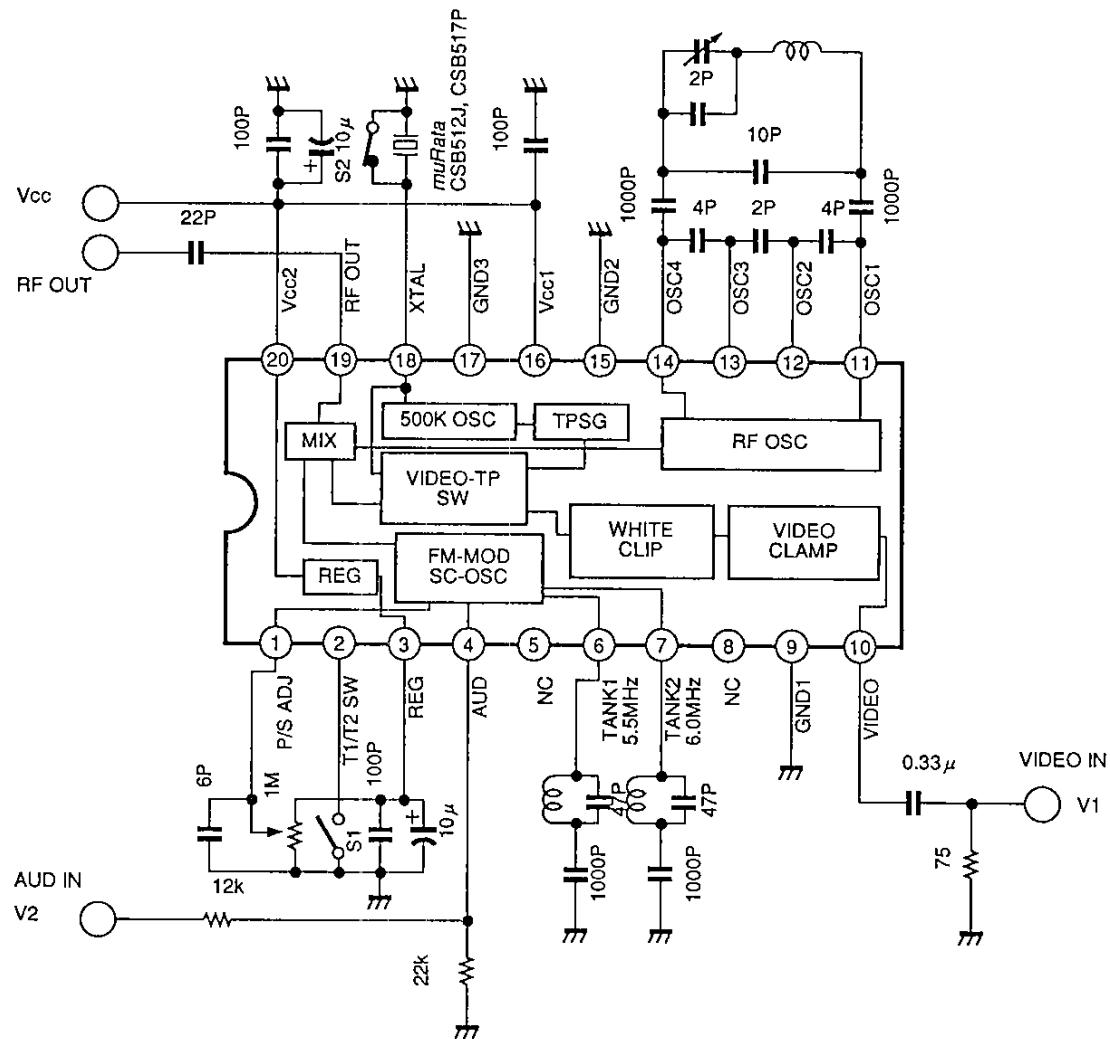
TPSG Waveform



Electrical Characteristics Test Circuit

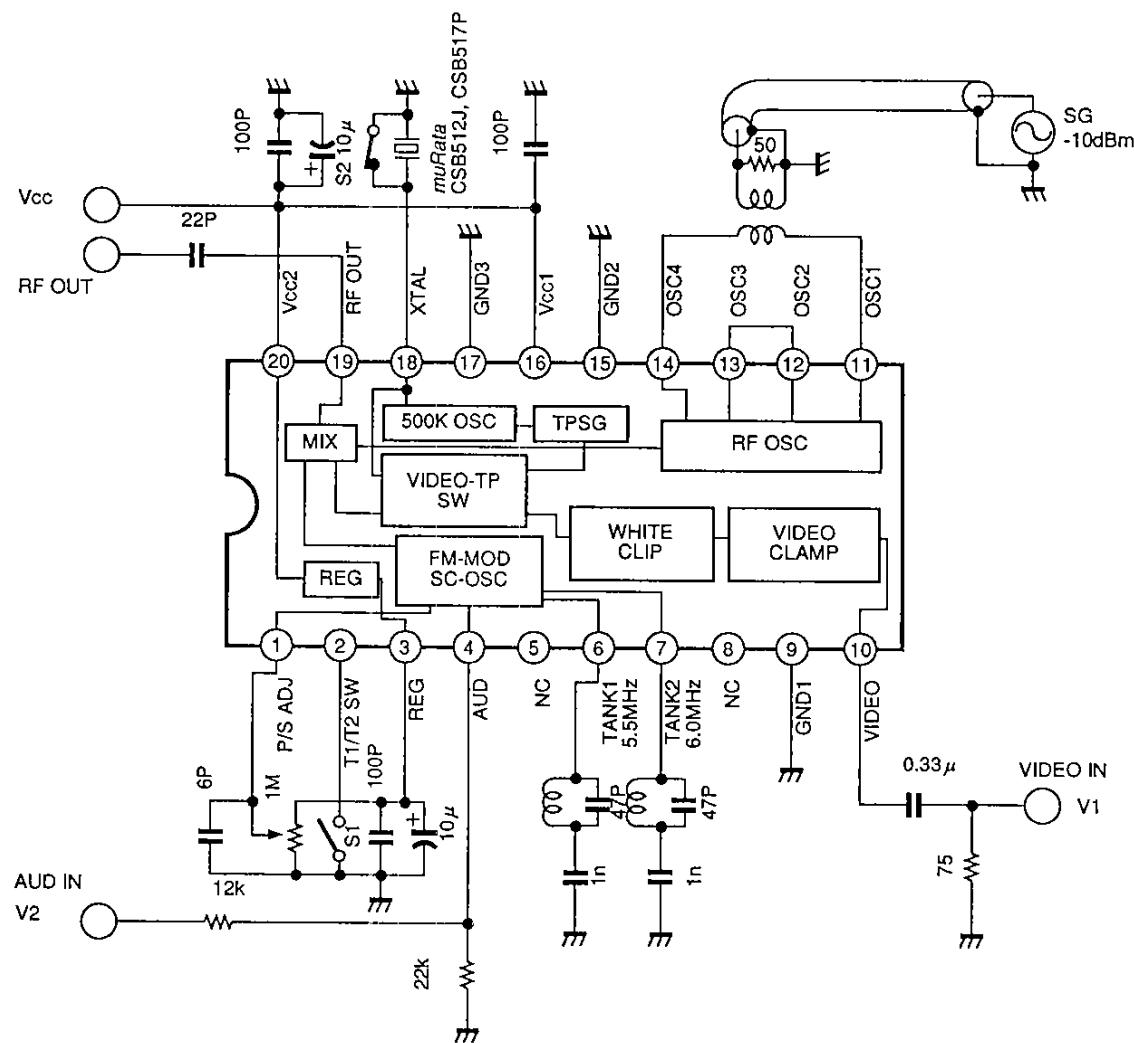


Application Circuit 1



Application circuits shown are typical examples illustrating the operation of the devices. Sony cannot assume responsibility for any problems arising out of the use of these circuits or for any infringement of third party patent and other right due to same.

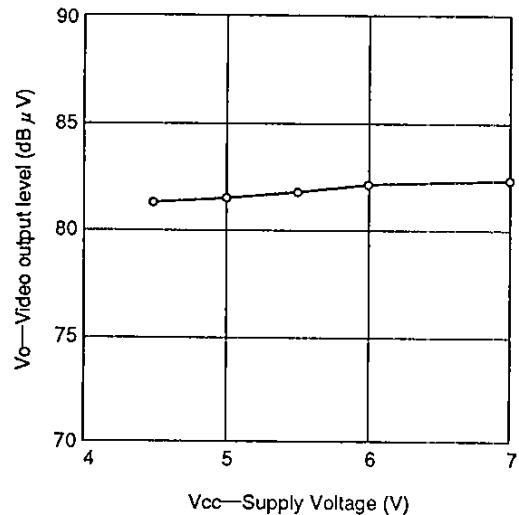
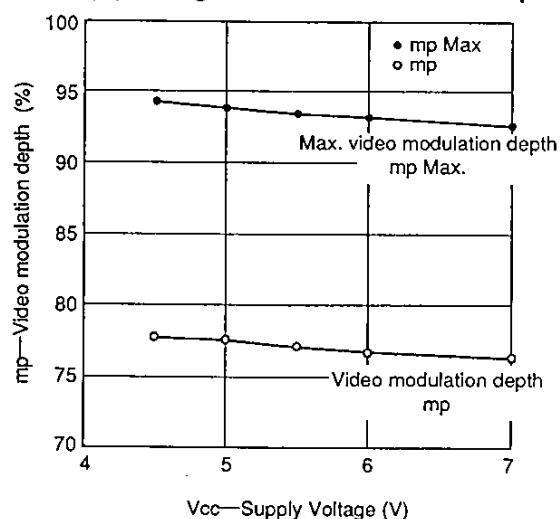
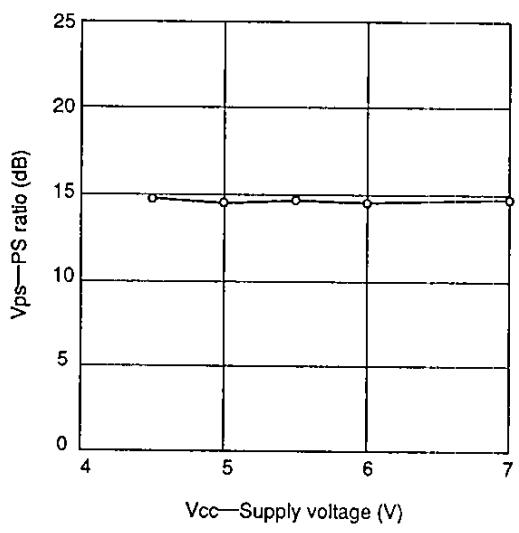
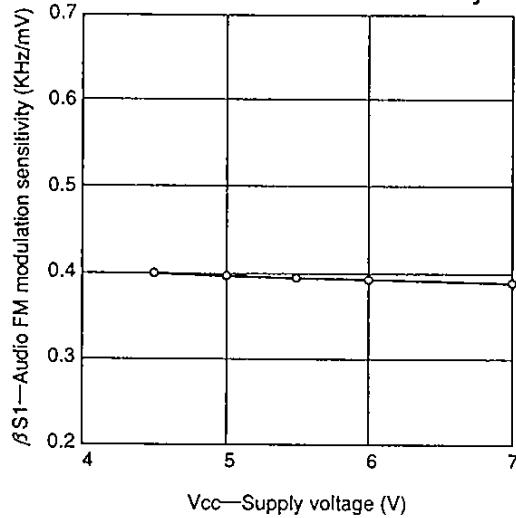
Application Circuit 2

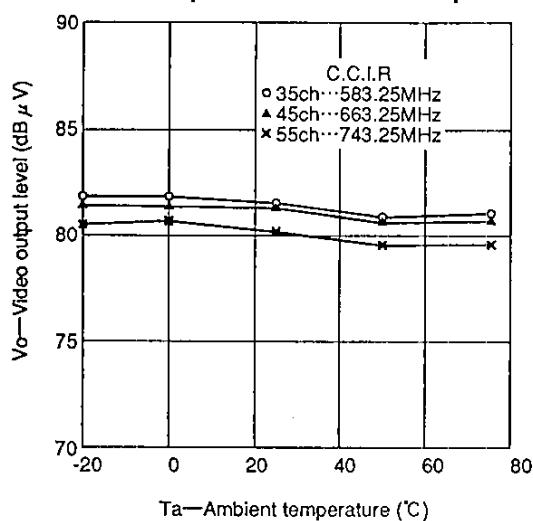
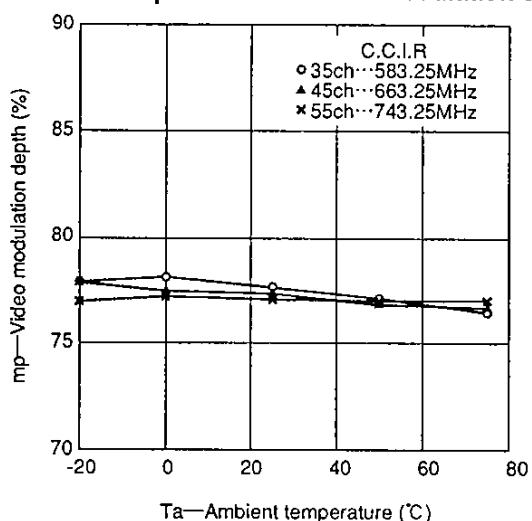
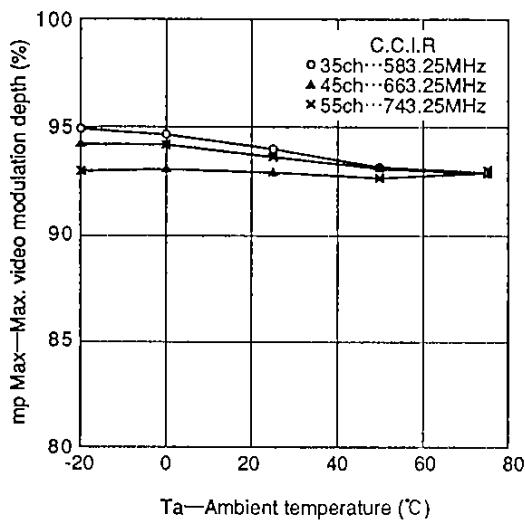
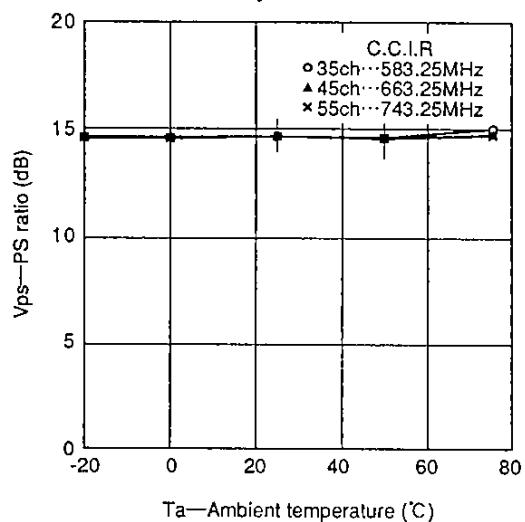
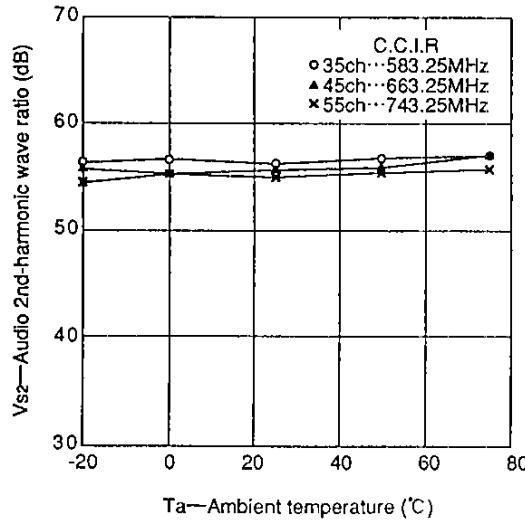
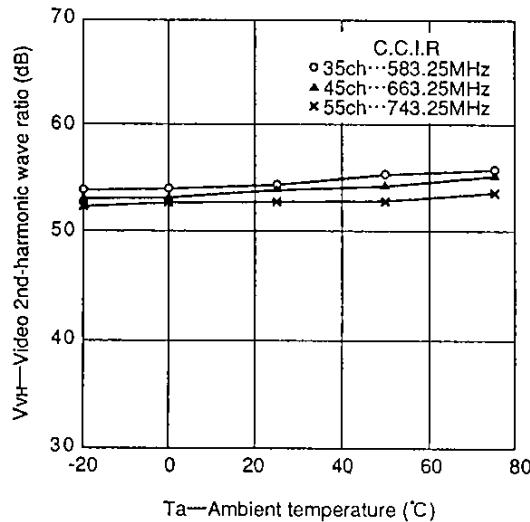


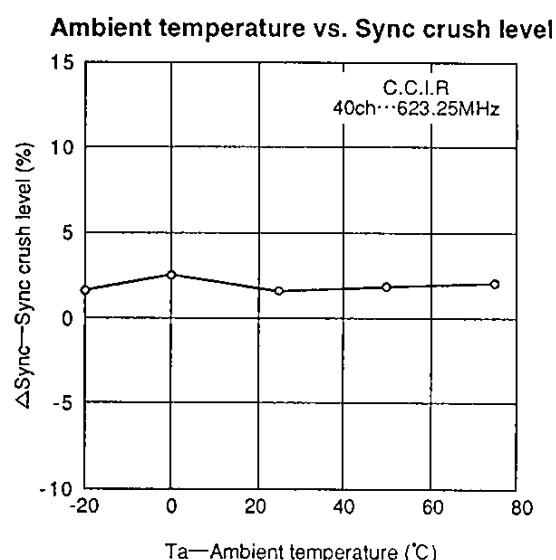
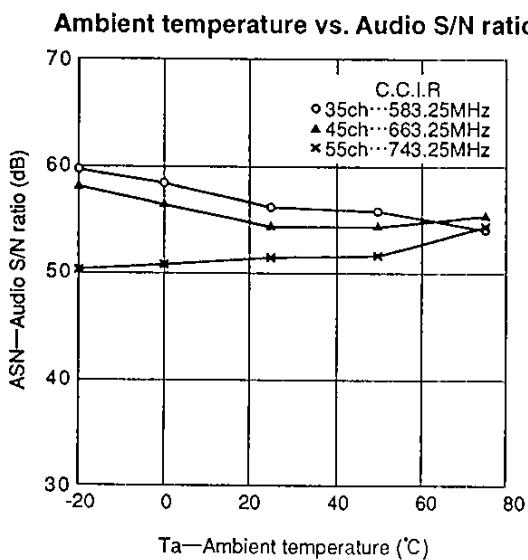
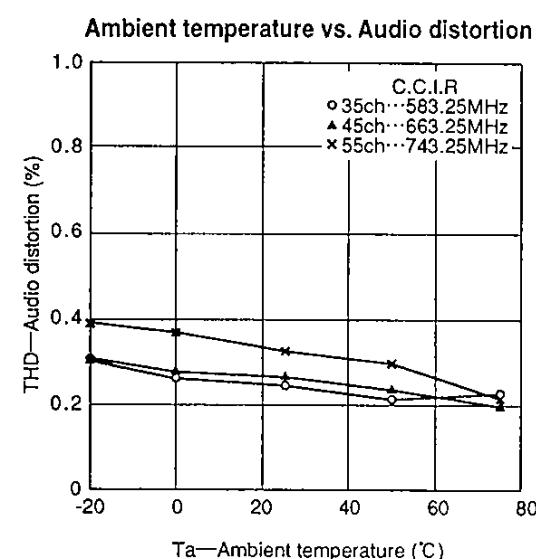
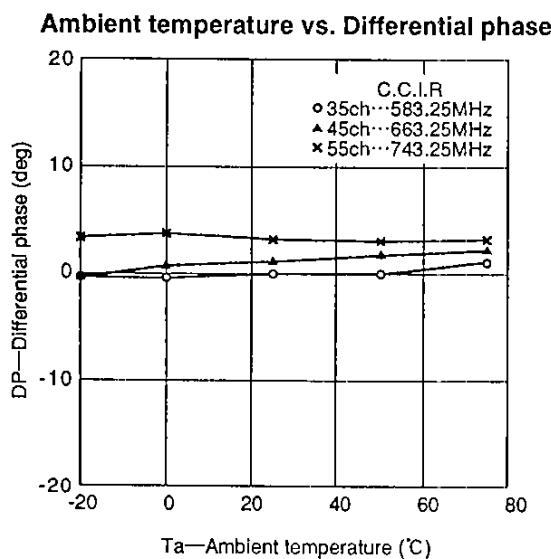
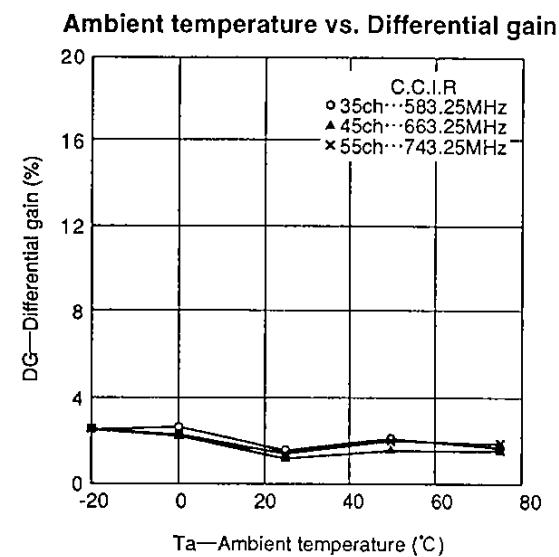
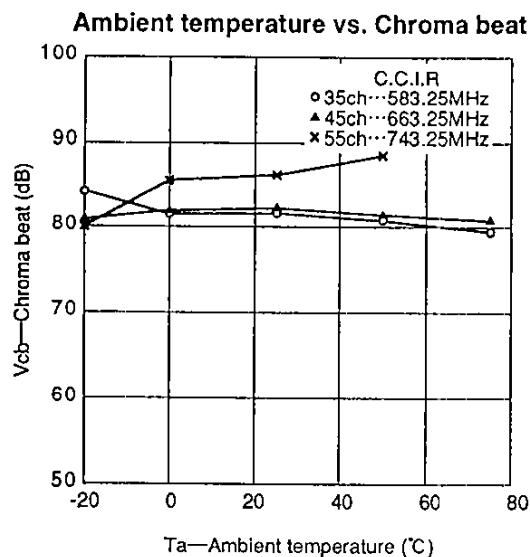
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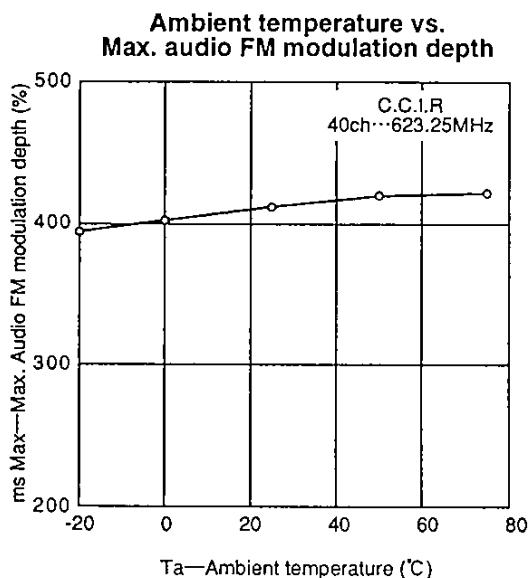
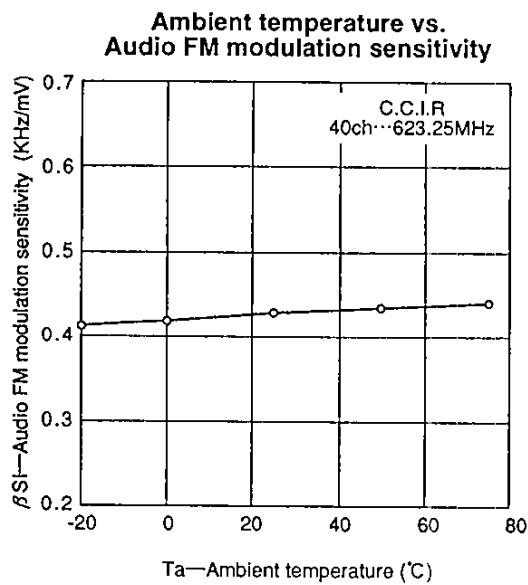
Example of Representative Characteristics

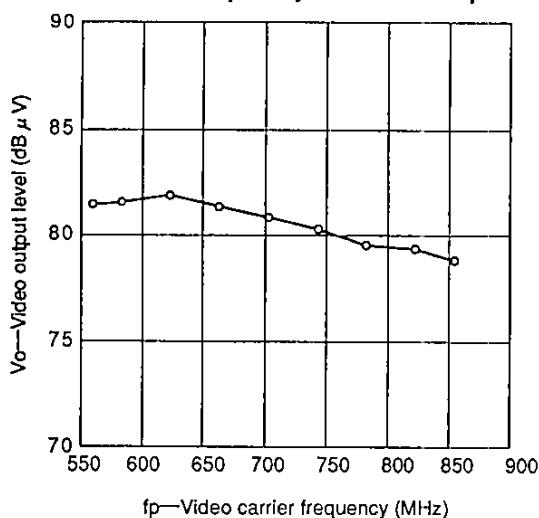
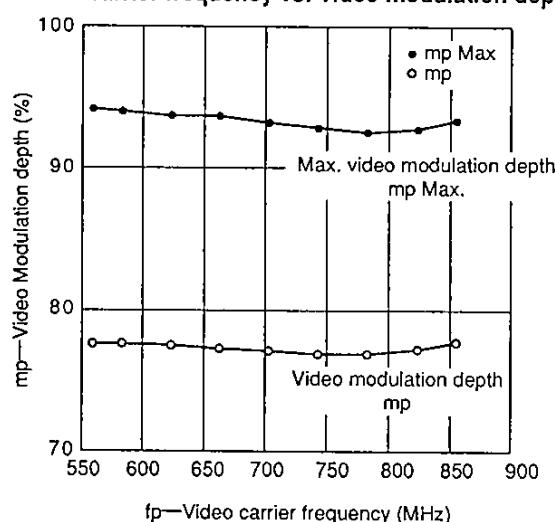
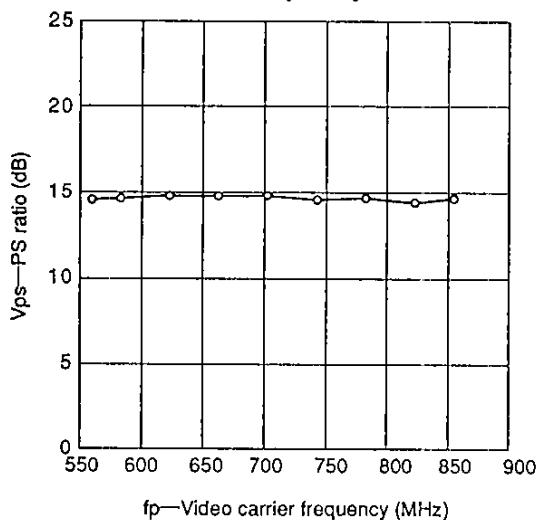
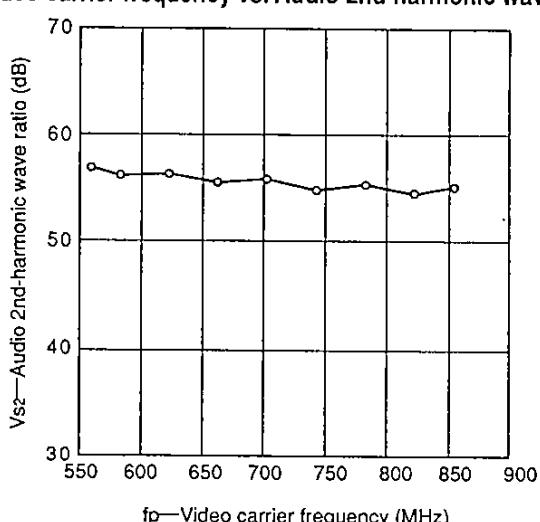
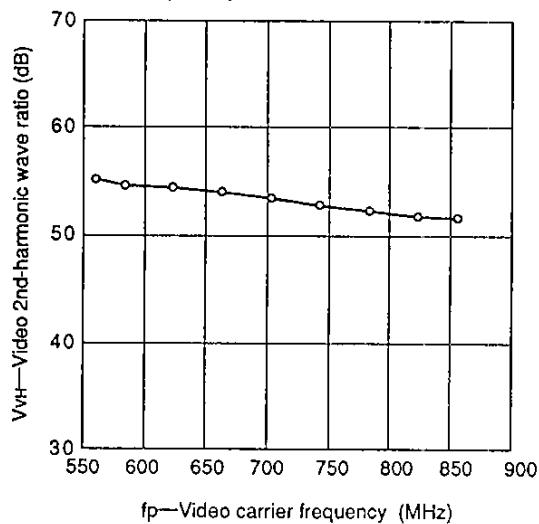
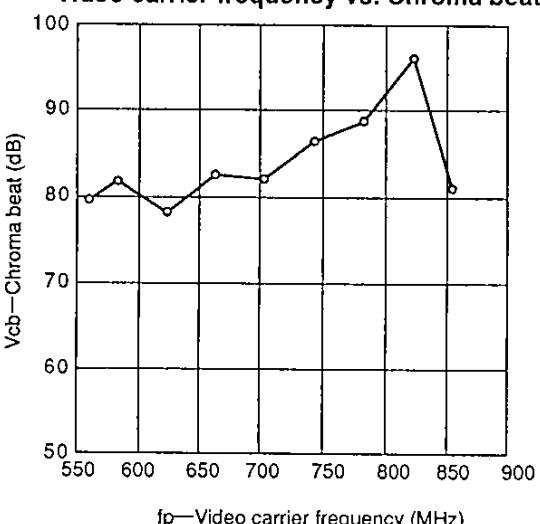
(fp=591.25MHz, Ta=25°C)

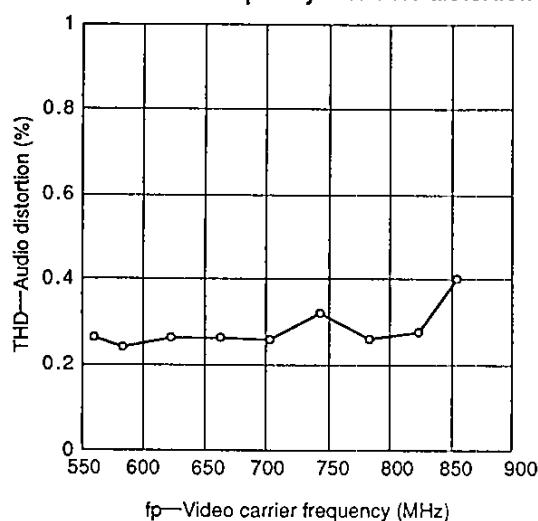
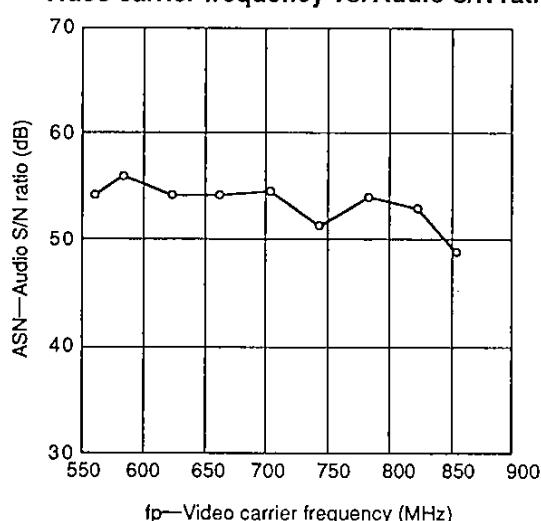
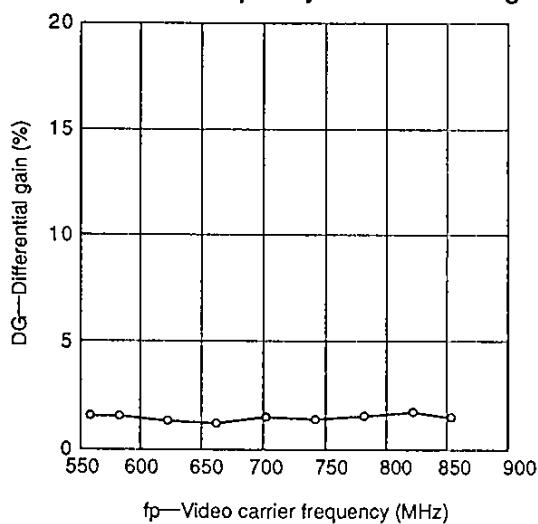
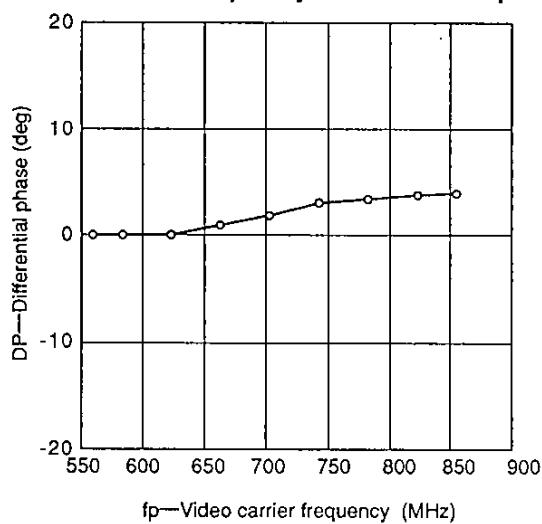
Supply voltage vs. Video output level**Supply voltage vs. Video modulation depth****Supply voltage vs. PS ratio****Supply voltage vs. Audio FM modulation sensitivity**

Ambient temperature vs. Video output level**Ambient temperature vs. Video modulation depth****Ambient temperature vs. Max. video modulation depth****Ambient temperature vs. PS ratio****Ambient temperature vs. Audio 2nd-harmonic wave ratio****Ambient temperature vs. Video 2nd-harmonic wave ratio**





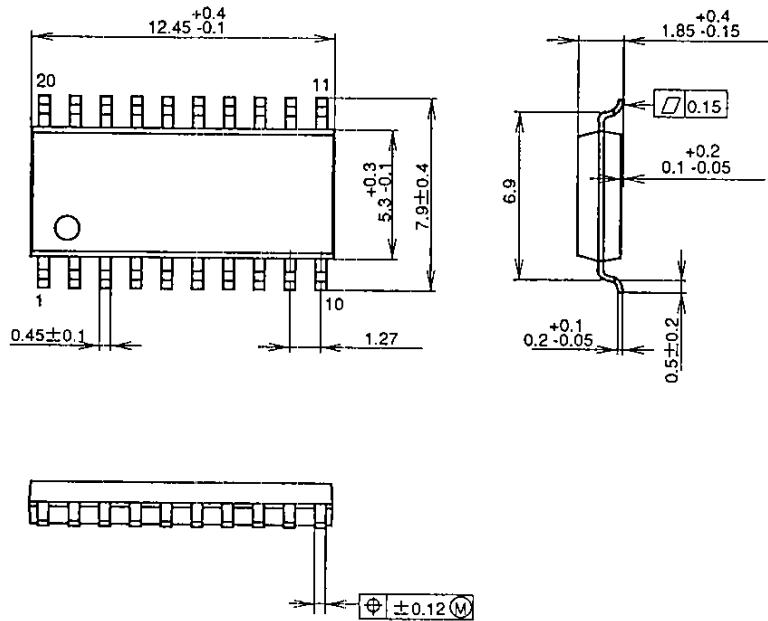
Video carrier frequency vs. Video output level**Video carrier frequency vs. Video modulation depth****Video carrier frequency vs. PS ratio****Video carrier frequency vs. Audio 2nd-harmonic wave ratio****Video carrier frequency vs. Video 2nd-harmonic wave ratio****Video carrier frequency vs. Chroma beat**

Video carrier frequency vs. Audio distortion**Video carrier frequency vs. Audio S/N ratio****Video carrier frequency vs. Differential gain****Video carrier frequency vs. Differential phase**

Package Outline

Unit: mm

20PIN SOP (PLASTIC) 300MIL



PACKAGE STRUCTURE

SONY CODE	SOP-20P-L01
EIAJ CODE	*SOP020-P-0300-A
JEDEC CODE	—

PACKAGE MATERIAL	EPOXY RESIN
LEAD TREATMENT	SOLDER PLATING
LEAD MATERIAL	COPPER ALLOY
PACKAGE WEIGHT	0.3g